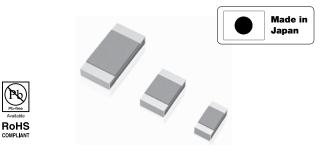
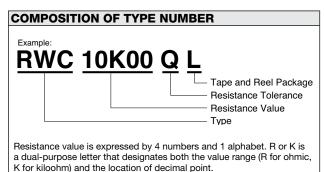
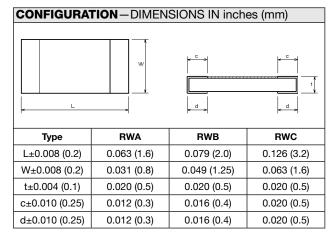
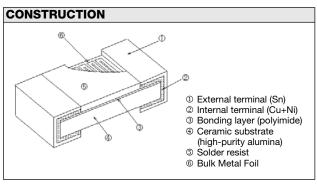


Precision SMD Bulk Metal® Foil Resistor (Wraparound)





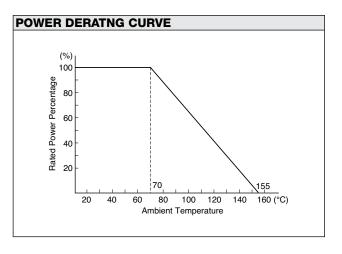




FEATURES

- High precision and stable Bulk Metal® Foil resister with 0603, 0805 and 1206 package
- TCR: 0±2 ppm/°C, 0±5 ppm/°C
- Resistance tolerance: up to ±0.01%
- Load-life stability: ±0.005% (typical, 70°C, 2000 hrs., rated power)
- No standard resistance value (example: 1K234Ω)
- MOQ: 100 pieces

TCR, RESISTANCE RANGE, TOLERANCE, RATED POWER								
Туре	TCR -25°C to +125°C (ppm/°C)	Resistance Range (Ω)	Resistance Tolerance (%)	Rated Power at 70°C (W)				
RWA	0±5	100 to 1k	±0.1(B)	0.1				
HWA	0±5	1k to 5k	±0.05(A)	0.1				
	0±10	10 to 30	±0.5(D)	0.2				
RWB	0±5	30 to 100	±0.1(B)					
NWD	0±2	100 to 1k	±0.05(A), ±0.1(B)					
	U±Z	1k to 10k ±0.02(Q), ±0.05(A)]				
	0±10	5 to 30	±0.5(D)	0.3				
RWC	0±5	30 to 100	±0.1(B)					
	0±2	100 to 1k	±0.02(Q), ±0.05(A), ±0.1(B)	0.3				
	U±Z	1k to 30k	±0.01(T), ±0.02(Q), ±0.05(A)					





PERFORMANCE							
PARAMETERS	TEST CONDITION	SPECIFICATION					
PARAMETERS	TEST CONDITION	MIL-PRF-55342	ALPHA Typical				
Max. Rated Operating Temperature		70°C					
Working Temperature Range		−65°C to	+155°C				
Maximum Working Voltage		RWA=22V, RWB=45V, RWC=95V					
Thermal Shock	-65°C/30 min.⇔+150°C/30 min. 100 cycles	±0.1%	±0.01%				
Overloading	Rated Voltage x 2.5, 5 sec.	±0.1%	±0.01%				
Low Temperature Storage	–65°C, No Load, 24 hrs.→ Rated Power, 45 min.	±0.1%	±0.01%				
Resistance to Soldering Heat	+260°C, 10 sec.	±0.2%	±0.01%				
Moisture Resistance	+65°C to -10°C, 90% RH to 98% RH, Rated Voltage, 10 cycles (240 hrs.)	±0.2%	±0.02%				
Life	70°C, Rated Power, 1.5 hrs. ON, 0.5 hrs. OFF, 2,000 hrs.	±0.5%	±0.005%				
High Temperature Exposure	155°C, No Load, 100 hrs.	±0.1%	±0.02%				

TAPE AND REEL PACKAGE (BASED ON EIA-481-1) [DIMENSIONS IN inches (mm)]																
Tape Dimensions									Reel Dimensions							
Sprocket Hole J Cavity 0.010 (0.25) max.																
Туре	A ±0.004 (0.1)	B ±0.004 (0.1)	C ±0.008 (0.2)	D ±0.002 (0.05)	E ±0.004 (0.1)	F ±0.004 (0.1)	G ±0.002 (0.05)	H ±0.004 (0.1)	J ±0.022 (0.55)	A 0/-0.059 (0/-1.5)	N +0.039/0 (+1/0)	B ±0.008 (0.2)	C ±0.031 (0.8)	D ±0.020 (0.5)	W1 +0.039/0 (+1/0)	W2 ±0.039 (1.0)
RWA	0.039 (1.0)	0.071 (1.8)	0.315 (8.0)	0.138 (3.5)	0.069 (1.75)	0.157 (4.0)	0.079 (2.0)	0.157 (4.0)	Dia. 0.061 (1.55)	Dia. 7.087 (180)	Dia. 2.362 (60)	Dia. 0.512 (13)	Dia. 0.827 (21)	0.079 (2)	0.354 (9)	0.512 (13)
RWB	0.057 (1.45)	0.089 (2.25)	0.315 (8.0)	0.138 (3.5)	0.069 (1.75)	0.157 (4.0)	0.079 (2.0)	0.157 (4.0)	Dia. 0.061 (1.55)	Reel Capacity						
RWC	0.075 (1.9)	0.138 (3.5)	0.315 (8.0)	0.138 (3.5)	0.069 (1.75)	0.157 (4.0)	0.079 (2.0)	0.157 (4.0)	Dia. 0.061 (1.55)							

PRECAUTION IN USING FACE-BONDED CHIP RESISTORS

1. Storage

Storage conditions or environment may adversely affect solderability of the exterior terminals. Do not store in high temperature and humidity. The recommended storage environment is lower than 40°C, has less than 70% RH humidity and is free from harmful gases such as sulphur and chlorine.

2. Caution in Soldering

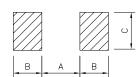
- IR and vapor phase reflow are recommended.
- Vacuum pick up is recommended for handling.
- If the use of a soldering iron becomes necessary, precautionary measures should be taken to avoid any possible damage / overheating.

3. Cleaning

Avoid the use of cleaning agents which could attack epoxy resins, which form part of the resistor construction.

4. Recommended Land Pattern

The dimensions of solder land must be determined in conformity with the size of resistors and with the soldering method. They are also subject to the mounting machine and the material of the substrate.



Туре	Α	В	С			
RWA	0.031 (0.8)	0.035 (0.9)	0.039 (1.0)			
RWB	0.031 (0.8)	0.047 (1.2)	0.055 (1.4)			
RWC	0.063 (1.6)	0.059 (1.5)	0.071 (1.8)			